



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-06
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T405Q-600H	BHIK*Z1G046T	A	998G	2017-02-06
	Amount	UoM	Unit type	ST ECOPACK Grade
	310.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	6.1-6.5-2.3	3	Through-hole	
Comment	IPAK TO-251			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BHK*21G046T					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.507	mg	supplier	die	Silicon (Si)	7440-21-3		1.976	mg	788278	6377
				supplier	metallization	Aluminium (Al)	7429-90-5		0.069	mg	27512	223
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	3190	26
				supplier	Passivation	Silicon Oxide	7631-86-9		0.018	mg	7177	58
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.011	mg	4386	35
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1594	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	7177	58
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	0.403	mg	160686	1300
Leadframe	Copper & its alloys	181.733	mg	supplier	alloy	Copper (Cu)	7440-50-8		181.496	mg	998696	585471
				supplier	alloy	Iron (Fe)	7439-89-6		0.182	mg	1001	587
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.055	mg	303	177
Soft solder	Solder	2.569	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.454	mg	955236	7916
				supplier	solder	Silver (Ag)	7440-22-4		0.064	mg	24912	204
				supplier	solder	Tin (Sn)	7440-31-5		0.051	mg	19852	165
Bonding wires	Other inorganic materials	0.779	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.779	mg	1000000	2513
				supplier	mold compound	Silica, vitreous	60676-86-0		103.276	mg	869993	333148
Encapsulation	Other Organic Materials	118.709	mg	supplier	mold compound	Epoxy resin	25068-38-6		11.871	mg	100001	38294
				supplier	mold compound	Phenol resin	29690-82-2		2.968	mg	25002	9574
				supplier	mold compound	Carbon Black	1333-86-4		0.594	mg	5004	1916
Connections coating	Solder	3.703	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.703	mg	1000000	11945